L Number	Hits	Search Text	DB	Time stamp
7	0	429/423.ccls. and plat$3 and wash$3 and dry$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/15 16:34
8	19	118/429.ccls. and plat$3 and wash$3 and dry$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/15 16:35
9	66	118/423-429.ccls. and plat$3 and wash$3 and dry$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/15 16:54
10	2	118/423-429.ccls. and plat$3 and wash$3 and dry$3 AND pit	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/15 16:54
-	2	6517894.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:34
-	84	204/269.ccls. and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:36
-	1	204/269.ccls. and substrate AND pit	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:39
-	1	204/269.ccls. and substrate AND pits	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:41
-	525	204/$.ccls. AND pits	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:42
-	25	204/$.ccls. AND pits AND electroplat$3 near10 layers	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:49
-	380	204/$.ccls. AND pit AND layer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:08
-	64	204/$.ccls. AND pit AND layer AND electroplat$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:50
-	10549	plat$3 AND pit AND layer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:09
-	1	(plat$3 AND pit AND layer AND substrate) AND 118/423.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:10
-	6405	plat$3 AND pit AND layer AND substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:15

-	65787	plat$3 AND pit AND layer AND substrate 204/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:15
-	187	plat$3 AND pit AND layer AND substrate AND 204/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:33
-	235	204/267.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:35
-	39	204/267.ccls. AND substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:38
-	3	204/267.ccls. AND substrate AND pit	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:40
-	65353	first adj layer same second adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:50
-	3656	first adj layer same second adj layer NEAR25 different	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:47
-	32	(first adj layer same second adj layer NEAR25 different) and 118/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:47
-	6	first adj layer same second adj layer AND 204/206.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:10
-	0	first adj layer same second adj layer SAME pit NEAR substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:13
-	17	first adj layer same second adj layer SAME pit NEAR10 substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:15
-	109	first adj layer same second adj layer SAME pit	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:20
-	0	first adj layer same second adj layer SAME pit AND 204/$.ccls. and 205/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:25
-	793	wire near10 pits	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:26
-	4	(wire near10 pits) and memory adj device	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:27
-	136	204/$.ccls. and first near5 solution same second near5 solution and wash$3 and dry$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/15 14:59

-	0	204/$.ccls. and first near5 solution same second near5 solution and wash$3 and dry$3 and fine adj pit	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/15 14:59
-	11	204/$.ccls. and first near5 solution same second near5 solution and wash$3 and dry$3 AND convey$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/15 15:00
-	136	204/$.ccls. and first near5 solution same second near5 solution and wash$3 and dry$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/15 15:08
-	572	204/269.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/15 15:09
-	30	204/269.ccls. and wash$3 and dry$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/15 15:09

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